

DISCUSSION OF THE AMENDMENT

Claim 1 has been amended by incorporating the subject matter of Claims 3 and 4 therein, additionally requiring that R^3 contain, in effect, a $-C \equiv C-$ group, and inserting that the $-CH_2-$ group, and the alkylene group having 2-30 atoms, may also be fluoro-substituted, as supported in the specification at page 8, lines 20 and 24. Claims 3 and 4 have been canceled as redundant. Claim 5 has been amended to depend on Claim 1. Claims 10-12 have each been amended to depend on Claim 8 only, and by inserting appropriate transitional language. Finally, new Claims 13-15 have been added to claim the subject matter deleted by the amendments to Claims 10-12, respectively.

No new matter is believed to have been added by the above amendment. Claims 1, 2 and 5-15 are now pending in the application.

REMARKS

Applicants thank the Examiner for the courtesy extended to Applicants' attorney during the interview held October 3, 2006, in the above-identified application. During the interview, Applicants' attorney explained the presently-claimed invention and why it is patentable over the applied prior art, and discussed other issues raised in the Office action. The discussion is summarized and expanded upon below.

The rejection of Claims 1-7 and 11 under 35 U.S.C. § 102(b) as anticipated by or, in the alternative, under 35 U.S.C. § 103(a) as obvious over U.S. 6,225,238 (Wu), is respectfully traversed. Wu discloses polycarbosilanes having a formula (I) for preparing dielectric coatings (column 4, lines 24-49). In said formula (I), R₁, R₇, and R₁₀ can be analogized to presently-recited R³. Wu discloses said R₁, R₇, and R₁₀ as independently representing a substituted or unsubstituted alkylene, cycloalkylene, or arylene group (column 4, lines 40-42). Wu neither discloses nor otherwise suggests formula (1) of the present claims. Accordingly, it is respectfully requested that this rejection be withdrawn.

The rejection of Claims 1, 2, 4-8, 10 and 11 under 35 U.S.C. § 102(b) as anticipated by or, in the alternative, under 35 U.S.C. § 103(a) as obvious over U.S. 5,877,080 (Aoi et al), is respectfully traversed. Aoi et al discloses an interlayer insulating film between a lower metallization layer and an upper metallization layer (column 1, lines 5-11), wherein the interlayer insulating film may comprise an organic polymer containing a polysiloxane skeleton (column 12, lines 31-32). However, Aoi et al neither discloses nor otherwise suggests formula (1) of the present claims. Accordingly, it is respectfully requested that this rejection be withdrawn.

The rejection of Claims 1-12 under 35 U.S.C. § 102(e) as anticipated by or, in the alternative, under 35 U.S.C. § 103(a) as obvious over U.S. 2002/0059899 (Seta et al), is respectfully traversed. Seta et al discloses a polysilane used as an interlayer insulating film

having a dual damascene structure (Abstract). The polysilane is derived from an organic silicon compound having as the main chains, bondings of silicon and silicon [0247] - [0248], which polysilane may be in the form of a single polymer, or alternatively, have a structure where two or more types of polysilane materials are bonded to one another through an oxygen atom, a nitrogen atom, fatty acid group or an aromatic group, and 114 such compounds, labeled [1-1] to [1-114], respectively, are exemplified [0249]. Of the 114 compounds, only compound [1-26] has a carbon-carbon triple bond. However, such a compound is excluded by formula (1) of the present claims. As Applicants' attorney pointed out during the above-referenced interview, in order to be consistent with the above-discussed disclosure in Seta et al of the requirement of silicon-silicon bonding [0247], the polysilane obtained therefrom must have Si-Si bonds. Formula (1) of the present claims represents a polycarbosilane, which is characterized by Si atoms being separated by C or C-containing groups.

For all the above reasons, it is respectfully requested that this rejection be withdrawn.

The rejection of Claims 1, 2, 4-7 and 9-12 under 35 U.S.C. § 102(e) as anticipated by or, in the alternative, under 35 U.S.C. § 103(a) as obvious over U.S. 6,614,096 (Kojima et al) is respectfully traversed. Kojima et al discloses a low dielectric constant material, preferably having a siloxane skeleton, more preferably a polysiloxane containing a methyl group (column 6, lines 13-19). However, Kojima et al neither discloses nor suggests formula (1) of the present claims. Accordingly, it is respectfully requested that the rejection over Kojima et al be withdrawn.

Applicants respectfully call the Examiner's attention to the Information Disclosure Statement (IDS) filed June 21, 2005. The Examiner is respectfully requested to initial the Form PTO 1449 submitted therewith, and include a copy thereof with the next Office communication.

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Moreover, since the date of the IDS is before the date of the Office Action and thus technically was part of the Official file as of the Office Action date, Applicants respectfully request that should the Examiner determine that a new ground of rejection needs to be made in the next Office Action relying in whole or in part on any of the references cited in the IDS, then said next Office Action not be made Final, even if the new rejection was necessitated by the present amendment to the claims.

Applicants respectfully submit that all of the presently-pending claims in this application are now in immediate condition for allowance. Accordingly, the Examiner is respectfully requested to pass this application to issue.

Respectfully submitted,

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